Irish Standard
I.S. EN 60068-2-83:2011

Environmental testing -- Part 2-83: Tests - Test Tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste (IEC 60068-2-83:2011 (EQV))

I.S. EN 60068-2-83:2011

Incorporating amendments/corrigenda issued since publication:

The National Standards Authority of Ireland (NSAI) produces the following categories of formal documents:

I.S. xxx: Irish Standard – national specification based on the consensus of an expert panel and subject to public consultation.

S.R. xxx: Standard Recommendation - recommendation based on the consensus of an expert panel and subject to public consultation.

SWiFT xxx: A rapidly developed recommendatory document based on the consensus of the participants of an NSAI workshop.

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EUROPEAN STANDARD

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EUROPÄISCHE NORM

EN 60068-2-83

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English version

Environmental testing - Part 2-83: Tests - Test Tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste

(IEC 60068-2-83:2011)

Essais d'environnement -
Partie 2-83: Essais -
Essais Tf: Essai de brasabilité des composants électroniques pour les composants pour montage en surface (CMS) par la méthode de la balance de mouillage utilisant de la pâte à braser
(CEI 60068-2-83:2011)

Umweltprüfungen -
Teil 2-83: Prüfungen -
Prüfung Tf: Prüfung der Lötbarkeit von Bauelementen der Elektronik für Oberflächenmontage (SMD) mit der Benetzungswaage unter Verwendung von Lotpaste
(IEC 60068-2-83:2011)

This European Standard was approved by CENELEC on 2011-10-12. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Ref. No. EN 60068-2-83:2011 E

Foreword

The text of document 91/975/FDIS, future edition 1 of IEC 60068-2-83, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60068-2-83:2011.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2012-07-12
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2014-10-12

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC [and/or CEN] shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 60068-2-83:2011 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-69	NOTE	Harmonized as EN 60068-2-69.
IEC 61189-5	NOTE	Harmonized as EN 61189-5.

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	EN/HD	Year
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60068-2-20	2008	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	2008
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 61190-1-3	-	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3	-

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CONTENTS

INTERNATIONAL ELECTROTECHNICAL COMMISSION

ENVIRONMENTAL TESTING –

Part 2-83: Tests – Test Tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste

FOREWORD

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International Standard IEC 60068-2-83 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/975/FDIS	91/992/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of patents as indicated below.

IEC takes no position concerning the evidence, validity and scope of patent rights.

The holders of the patent rights have assured the IEC that they are willing to negotiate licences either free of charge or under reasonable and non-discriminatory terms and conditions with applicants throughout the world. In this respect, the statement of the holders of these patent rights are registered with IEC. Information may be obtained as indicated below.

a) EU patent 0920488.4 “Synchronous test method for assessing soldering pastes”[1]

Gen3 Systems LTD

Unit B2

Armstrong Mall

Farnborough GU14 0NR

United Kingdom

b) JP Patent 2630712 “Testing method of characteristics of solder paste and the equipment for the test”

Malcom Co., Ltd

4-15-10 Honmachi, Shibuya-ku

Tokyo, 151-0071

Japan

c) Patent JP 3789041 “Solderability measuring apparatus”

Patent JP 3552061 “Solderability tester and solderability test method”

Patent JP 3498100 “Method and device for testing solderability and microcrucible for testing”

Patent JP 3153884 “Measuring device for soldering performance of cream solder”

Tarutin Kester Co., Ltd.

2-20-11 Yokokawa,

Sumida-ku

Tokyo, 130-0003

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d) Sony Corporation

1-7-1 Konan Minato-ku

Tokyo 108-0075

Japan

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1 Status of patent: Pending.

ISO (www.iso.org/patents) and IEC (http://patents.iec.ch) maintain on-line data bases of patents relevant to their standards. Users are encouraged to consult the data bases for the most up to date information concerning patents.